## Thermal Laser Separation for PERC and SHJ Solar Cells

Latest results at Fraunhofer ISE



Puzant Baliozian, Anna Münzer, Elmar Lohmüller

Fraunhofer Institute for Solar Energy Systems ISE

PV magazine webinar Online, 03.06.2021

www.ise.fraunhofer.de

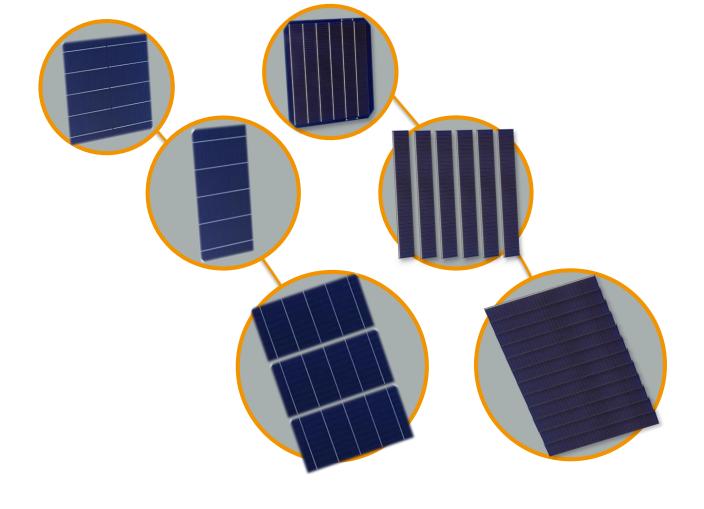
# **Approach Separated Solar Cells**

Full wafer-sized solar cells...

After contact formation

...separated
less current per cell

...interconnected into strings ribbon-based or shingled



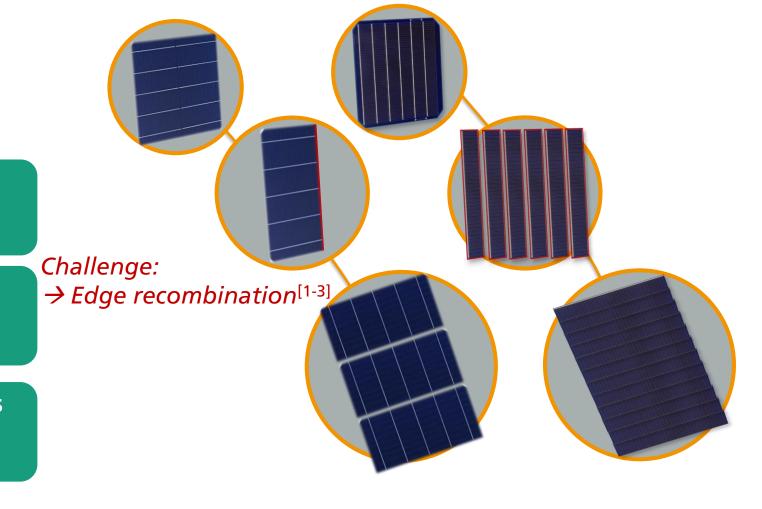
## **Separated Solar Cells**

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Higher impact for smaller cells with high perimeter-to-area ratios!



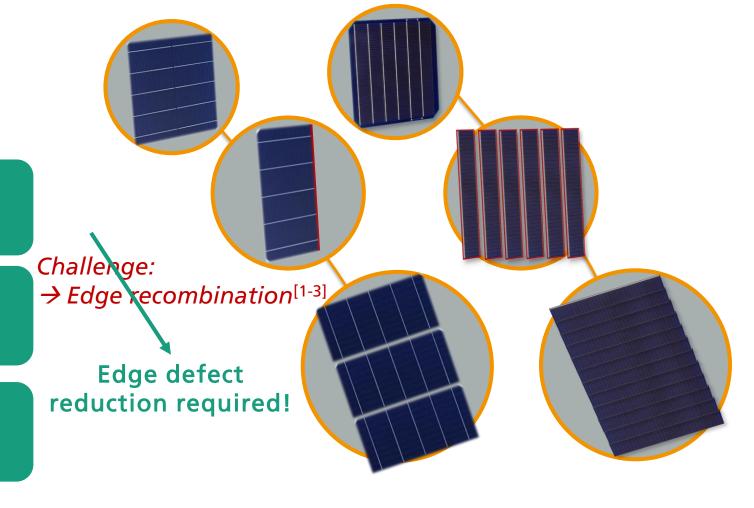
## **Separated Solar Cells**

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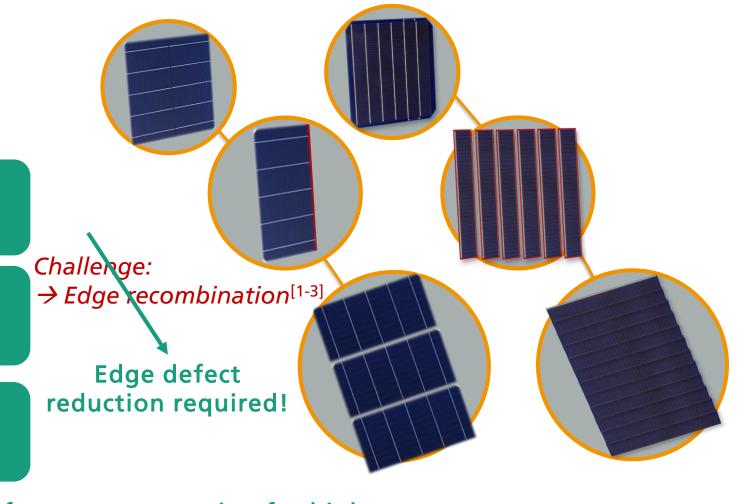
## **Separated Solar Cells**

Full wafer-sized solar cells...

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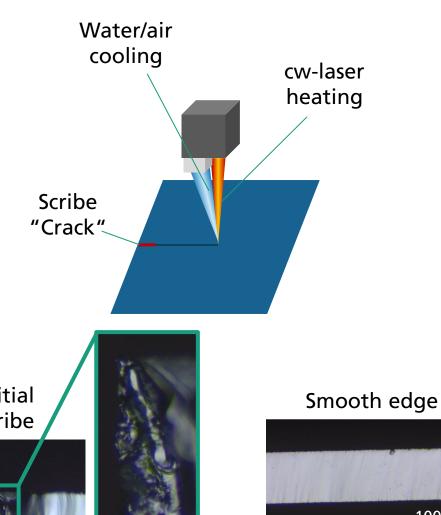


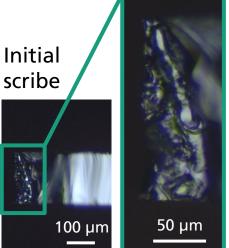
Defect poor separation for high electrical performance in addition to the mechanical stability



## **Thermal Laser Separation**

- Thermal laser separation (TLS)<sup>[1,2]</sup>
  - 1. Scribe process: initiates short crack (ablation)
  - 2. Cleave process: continuous wave (cw) laser-based heating and water/air cooling (no ablation)







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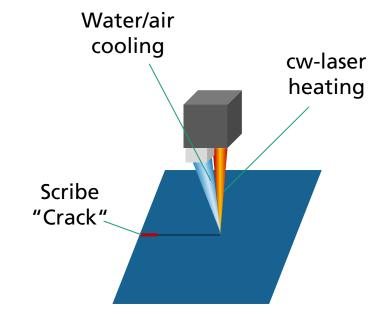
## **Thermal Laser Separation**

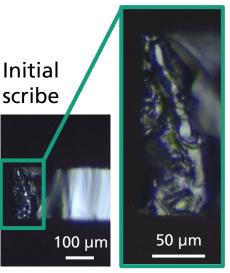
- Thermal laser separation (TLS)<sup>[1,2]</sup>
  - 1. **Scribe** process: initiates short crack (ablation)
  - 2. Cleave process: continuous wave (cw) laser-based heating and water/air cooling (no ablation)
- Cleave process
  - → Temperatures below silicon melting point
- Might have an impact on already existing passivation layers of solar cells e.g.
  - Aluminum oxide (AlO<sub>x</sub>) and silicon nitride (SiN<sub>x</sub>) in PERC<sup>[3]</sup>

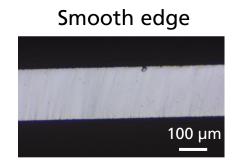
[1] H.U. Zuehlke, CS Compound Semiconductor (2016)

[2] https://3d-micromac.de/laser-mikrobearbeitung/produkte/microdice/

Hydrogenated amorphous silicon in SHJ<sup>[4]</sup>



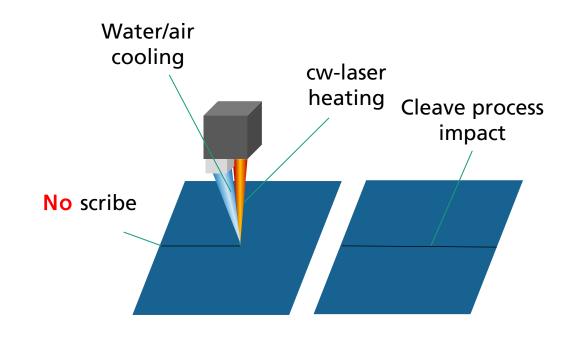




(online 2021)

## **Cleave Process Optimization Method**[1]

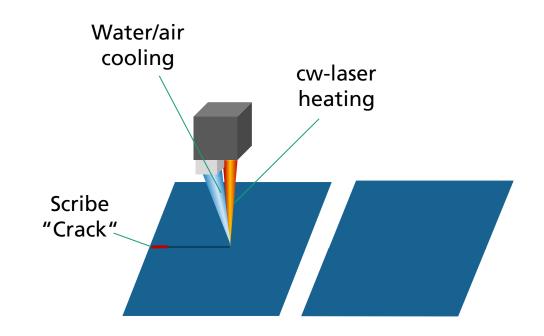
- Only cleave process (no scribe)
  - $\blacksquare$  No separation  $\rightarrow$  just cleave process impact



| Scribe process | Cleave<br>process | After processing<br>wafer | Studied impact |
|----------------|-------------------|---------------------------|----------------|
| OFF            | ON                | Full format               | Cleave process |

## **Cleave Process Optimization Method**<sup>[1]</sup>

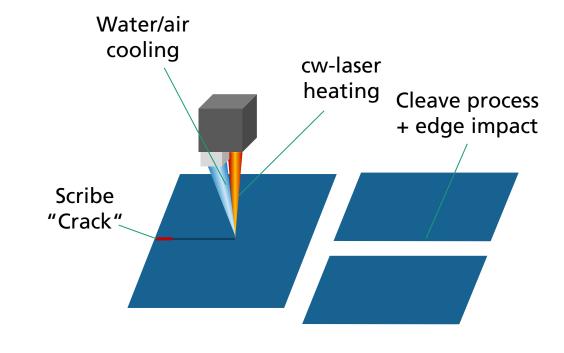
- Only cleave process (no scribe)
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- Complete TLS (scribe + cleave)
  - Complete separation → cleave process and newly formed edge impact



| Scribe<br>process | Cleave<br>process | After processing wafer | Studied impact           |
|-------------------|-------------------|------------------------|--------------------------|
| OFF               | ON                | Full format            | Cleave process           |
| ON                | ON                | Separated              | Cleave process<br>+ edge |

## **Cleave Process Optimization Method**[1]

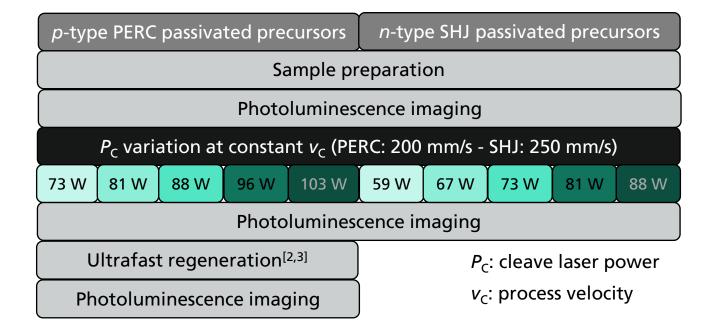
- Only cleave process (no scribe)
  - $\blacksquare$  No separation  $\rightarrow$  just cleave process impact
- Complete TLS (scribe + cleave)
  - Complete separation → cleave process and newly formed edge impact
- Photoluminescence imaging<sup>[2]</sup> before and after cleave parameter variation



| Scribe<br>process | Cleave<br>process | After processing<br>wafer | Studied impact           |
|-------------------|-------------------|---------------------------|--------------------------|
| OFF               | ON                | Full format               | Cleave process           |
| ON                | ON                | Separated                 | Cleave process<br>+ edge |

## **Experimental Process Flow**<sup>[1]</sup>

- Study the impact of cleave laser on non-metallized passivated precursors
  - p-type Cz-Si PERC
  - n-type Cz-Si SHJ



PERC: passivated emitter and rear cell

SHJ: silicon heterojunction



### Results<sup>[1]</sup>

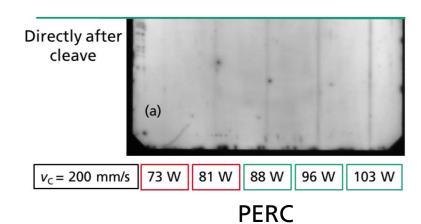
#### PERC:

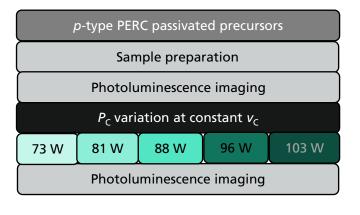
- PL signal drop (△PL<sub>S</sub>) measured directly after cleave process
- $\blacksquare$   $\triangle PL_{S}$  dependent on  $P_{C}$

 $P_{\rm C}$ : cleave laser power

 $v_{\rm C}$ : process velocity

## Lower PL signal (darker regions) means larger defects





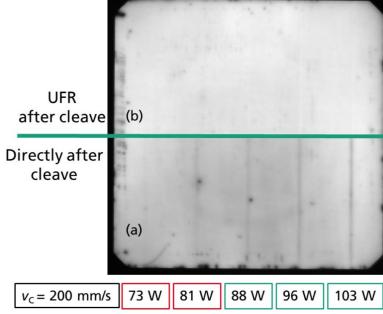
### Results<sup>[1]</sup>

#### PERC:

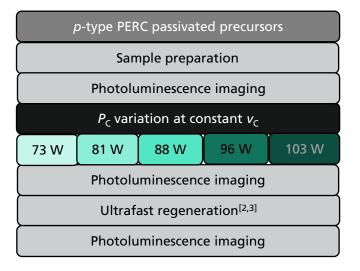
- PL signal drop ( $\triangle PL_{s}$ ) measured directly after cleave process
- $\Delta PL_s$  dependent on  $P_c$
- PL regain after UFR process
  - Reversible impact
  - No permanent damage

UFR: ultra fast regeneration  $P_{C}$ : cleave laser power  $v_{\rm C}$ : process velocity

## Defects disappear



**PERC** 



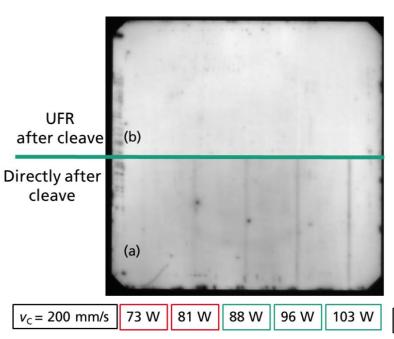
© Fraunhofer ISE

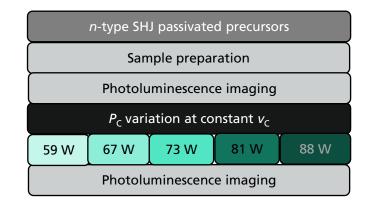
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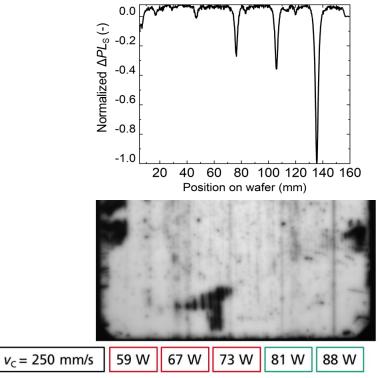
#### PERC:

- PL signal drop (△PL<sub>S</sub>) measured directly after cleave process
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- PL regain after UFR process
  - Reversible impact
  - → No permanent damage
- SHJ:
  - PL signal drop ( $\triangle PL_S$ ) measured (dependent on  $P_C$ )

UFR: ultra fast regeneration  $P_{C}$ : cleave laser power  $V_{C}$ : process velocity



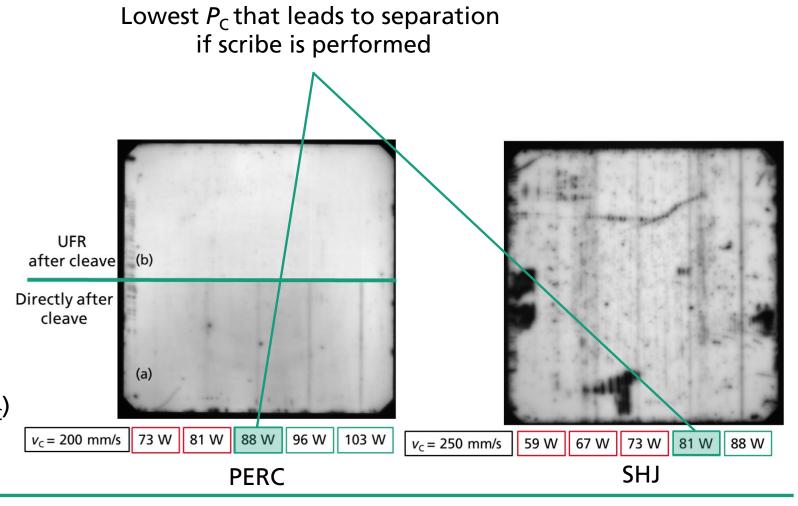




### Results<sup>[1]</sup>

#### PERC:

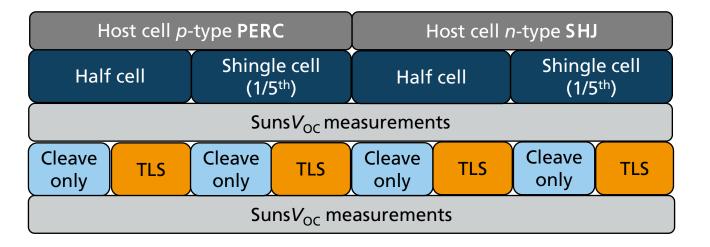
- PL signal drop (△PL<sub>S</sub>) measured directly after cleave process
- $\blacksquare$   $\triangle PL_{S}$  dependent on  $P_{C}$
- PL regain after UFR process
  - Reversible impact
  - → No permanent damage
- SHJ:
  - PL signal drop ( $\triangle PL_s$ ) measured (dependent on  $P_c$ )





## Metallized Host Cells – Experimental Process Flow<sup>[1]</sup>

- PERC and SHJ cells fabricated
  - Half cell format
  - Shingle cell format (shingle cell width = 31.35 mm)
- Characterization by SunsV<sub>OC</sub> measurement<sup>[2-4]</sup>
  - Influence on the open-circuit voltage  $V_{OC}$  and pseudo-fill factor pFF





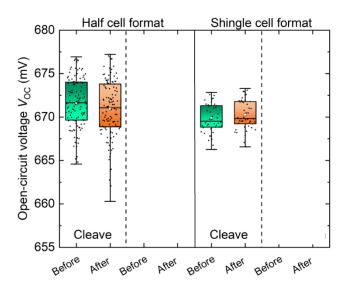
[4] D. Bertrand et al., IEEE JPV (2017)

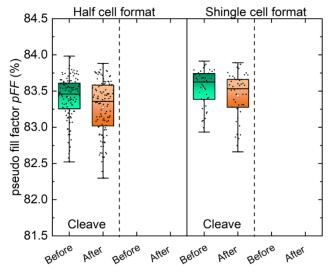
16

Only cleave process:

Minor impact on V<sub>oc</sub> and pFF

#### **PERC**





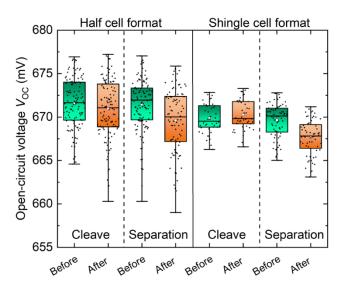
#### Only cleave process:

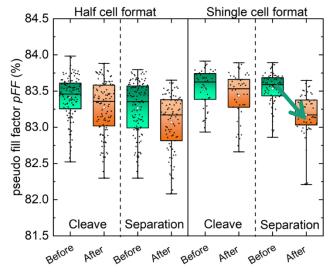
Minor impact on V<sub>oc</sub> and pFF

#### Complete separation:

- Few mV drop for half and shingle cells
- Highest pFF drop 0.4%<sub>abs</sub> recorded after complete separation into shingle cells

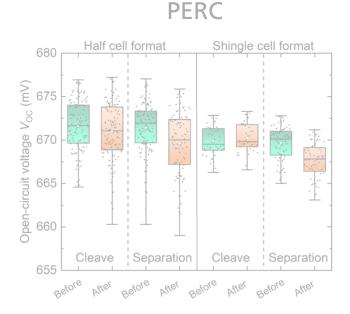
#### **PERC**

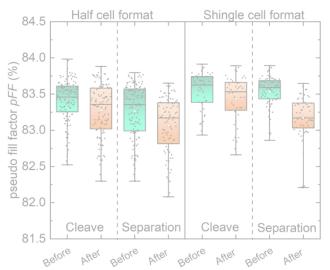


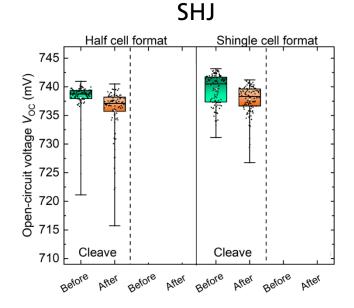


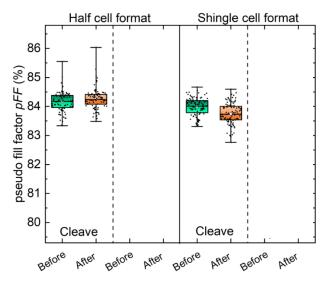
#### Only cleave process:

- Slight drop in V<sub>oc</sub>
- Minor impact on pFF only in the case of shingle cells







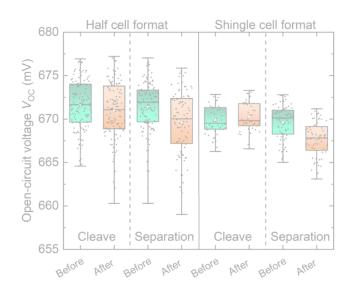


#### Only cleave process:

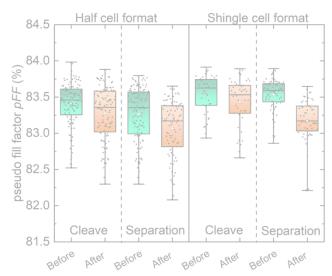
- Slight drop in  $V_{OC}$
- Minor impact on pFF only in the case of shingle cells

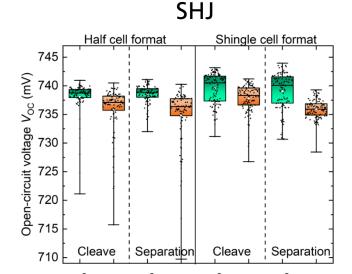
#### Complete separation leads:

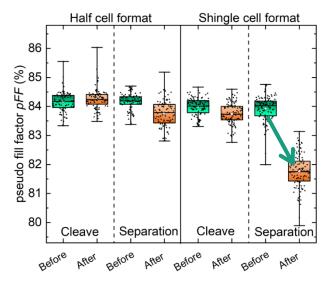
- V<sub>OC</sub> loss in the case of shingles around 4 mV
- *pFF* drop
  - Half cells: 0.4%<sub>abs</sub>
  - Shingle cells: 2.1%<sub>abs</sub>



**PERC** 







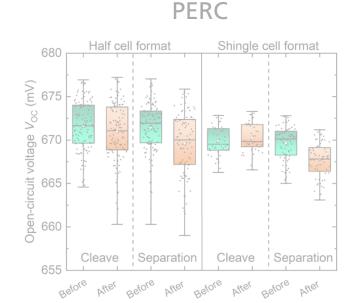
#### Only cleave process:

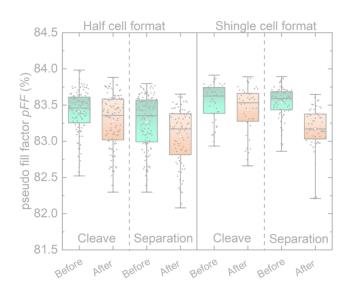
- Slight drop in V<sub>oc</sub>
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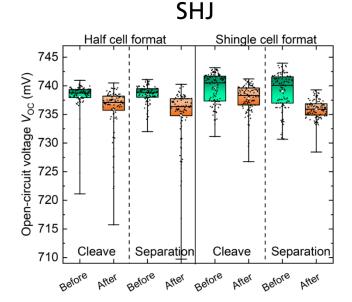
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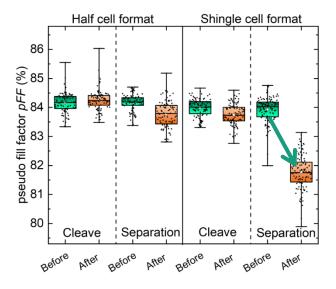
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- pFF drop
  - Half cells: 0.4%<sub>abs</sub>
  - Shingle cells: 2.1%<sub>abs</sub>

Deduction: main loss due to newly formed edge for both PERC and SHJ



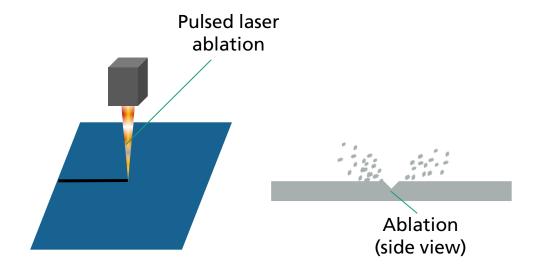






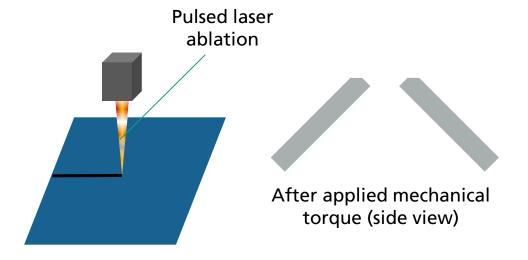
## **Comparison of Separation Processes**

- Laser scribing mechanical cleaving (LSMC) "conventional" separation<sup>[1,2]</sup>:
  - Scribe by a pulsed laser over the whole separation path length (ablation)



## **Comparison of Separation Processes**

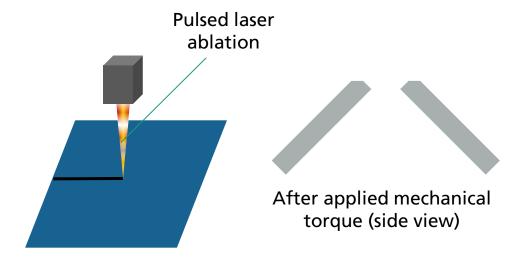
- Laser scribing mechanical cleaving (LSMC) "conventional" separation<sup>[1,2]</sup>:
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## **Comparison of Separation Processes**

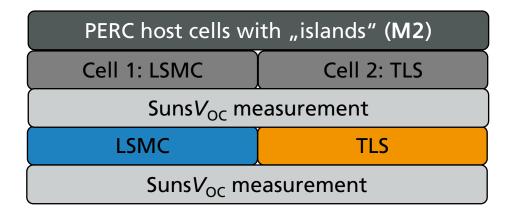
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  - Mechanical cleaving (breaking)

 Separation processes on PERC solar cells experimentally investigated

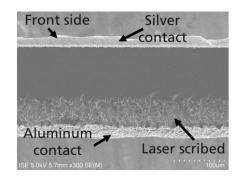


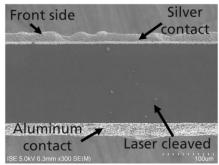
### **Small-sized PERC Solar Cells**

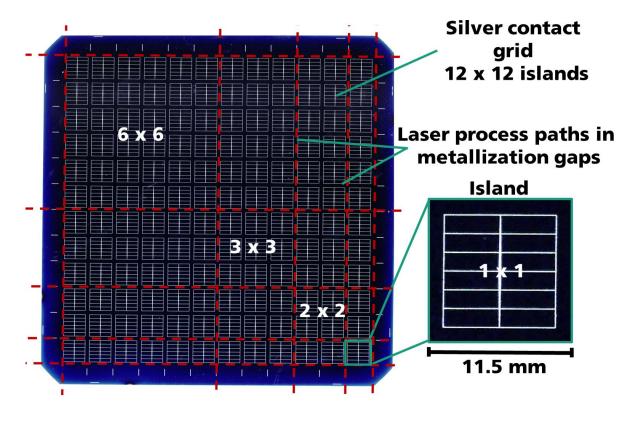
■ Smaller cells → higher edge recombination impact



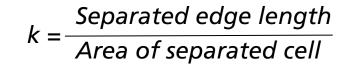
Separation from emitter-free side (rear side)



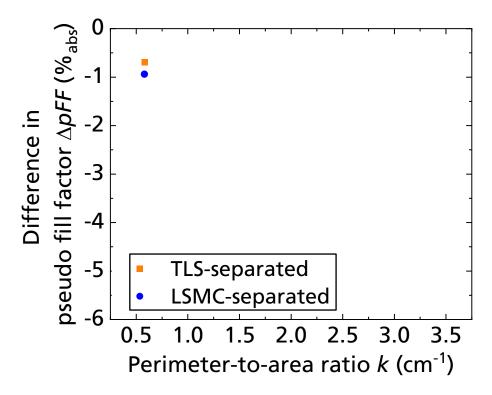




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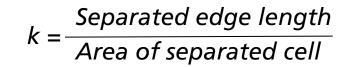


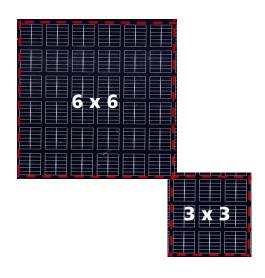


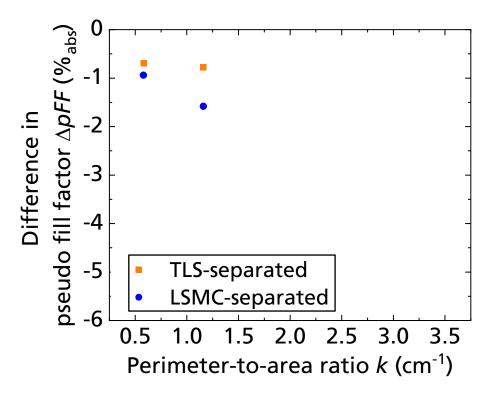
$$\triangle pFF = pFF_a - pFF_b$$

*pFF*<sub>a</sub>: after separation

### **Small-sized PERC Solar Cells**



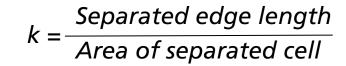


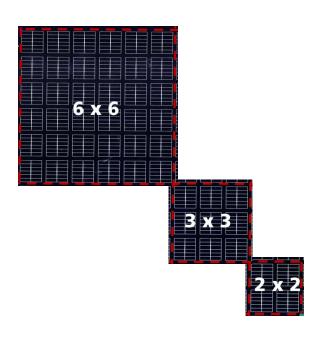


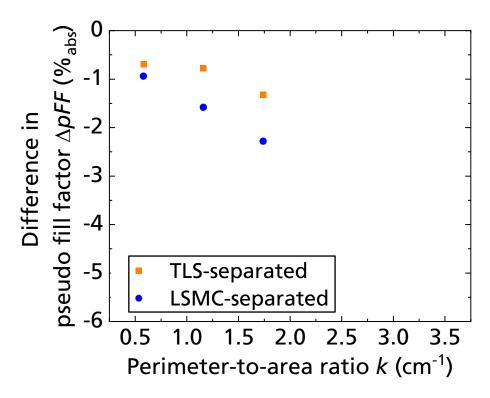
$$\Delta pFF = pFF_a - pFF_b$$

*pFF*<sub>a</sub>: after separation

### **Small-sized PERC Solar Cells**





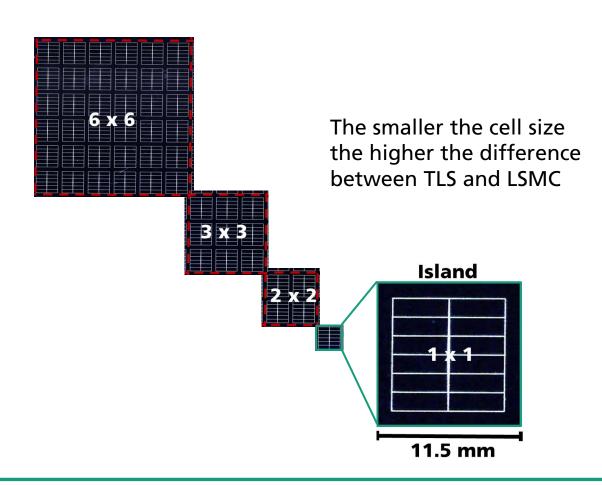


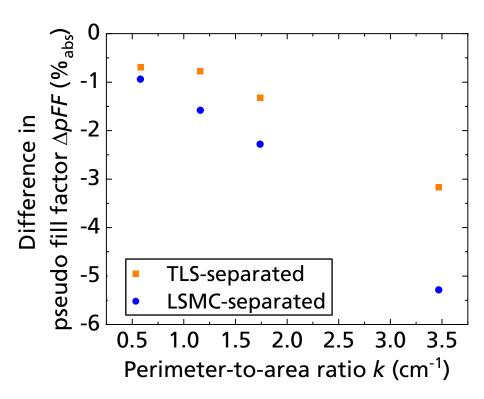
$$\triangle pFF = pFF_a - pFF_b$$

*pFF*<sub>a</sub>: after separation

### **Small-sized PERC Solar Cells**

$$k = \frac{Separated\ edge\ length}{Area\ of\ separated\ cell}$$



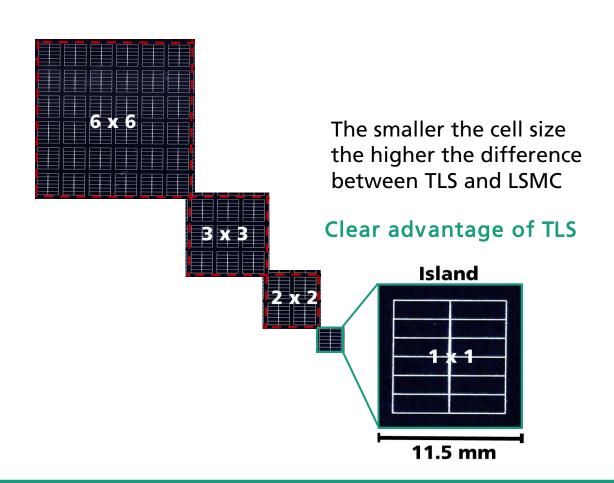


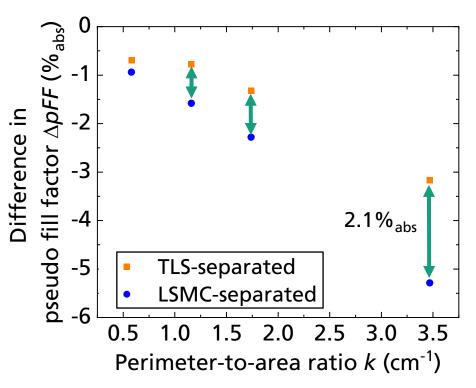
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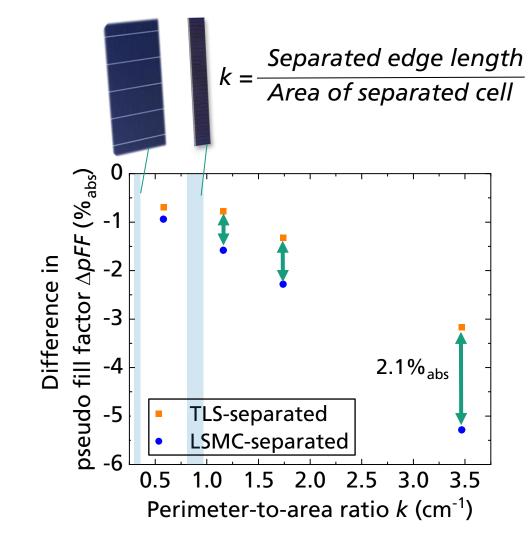
$$\triangle pFF = pFF_a - pFF_b$$

*pFF*<sub>a</sub>: after separation

# **Separation Process Comparison Small-sized PERC Solar Cells**

- Considering the formats
  - M2 M12 half cells
  - M2 M12 shingle cells (1/6th middle shingles)

- The smaller the separated cell size the more important is a defect poor edge
- Additional edge passivation is desired!



$$\triangle pFF = pFF_a - pFF_b$$

*pFF*<sub>a</sub>: after separation

 $pFF_b$ : before separation

Passivated Edge Technology (PET)

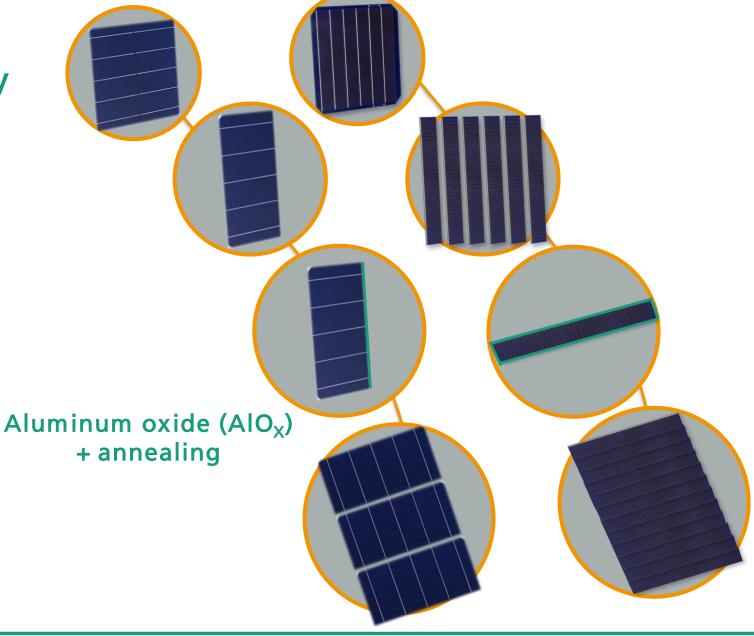
Full wafer-sized solar cells...

After contact formation

...separated
less current per cell

...edge passivation with Passivated Edge Technology (PET) *treatment*<sup>[1,2]</sup>

...interconnected into strings





## **Passivated Edge Technology**

**Experiment – Lab Scale**<sup>[1]</sup>

PERC Host cells

Suns $V_{\rm OC}$  measurement

Rear side LSMC

Rear side TLS

Suns $V_{\rm OC}$  measurement

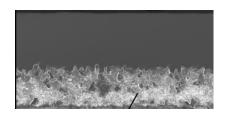
AlO<sub>x</sub> deposition

Suns $V_{\rm OC}$  measurement

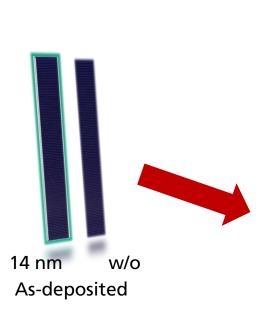
Annealing

Suns $V_{\rm OC}$  measurement







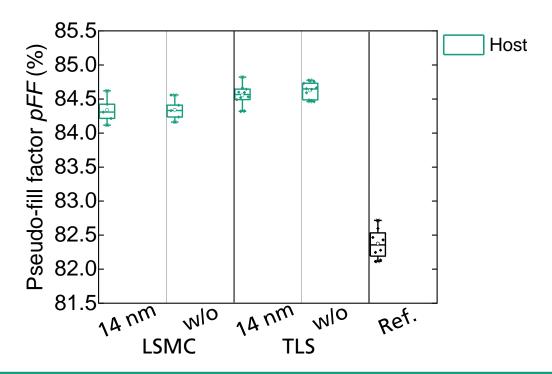




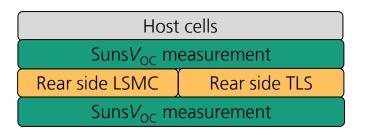
## Suns V<sub>OC</sub> Measurements<sup>[1]</sup>

 Host cells measured and pFF values considered

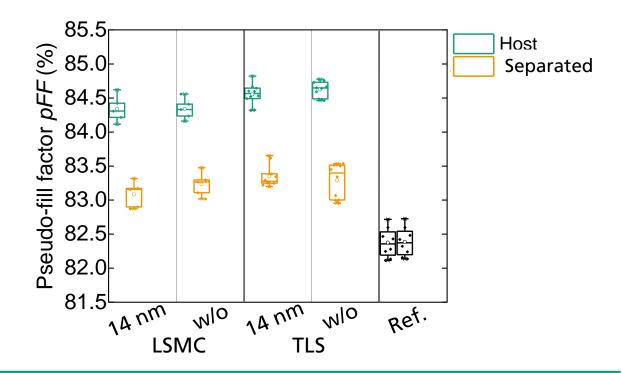




## Suns $V_{OC}$ Measurements - Separation<sup>[1]</sup>

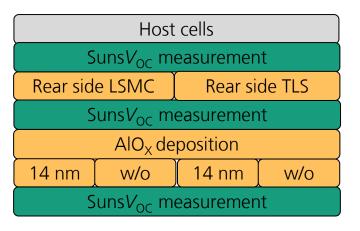


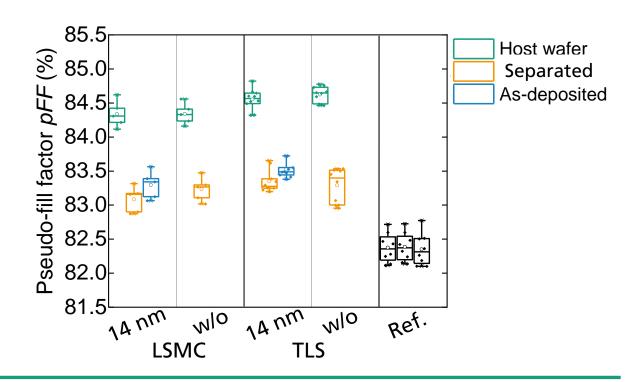
- Host cells measured and pFF values considered
- Similar drops in pFF for TLS and LSMC processes



## Suns $V_{OC}$ Measurements - Deposition<sup>[1]</sup>

- Host cells measured and pFF values considered
- Similar drops in pFF for TLS and LSMC processes
- Minor increase due to deposition

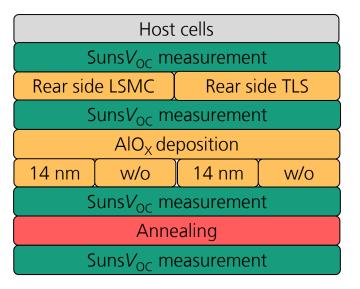


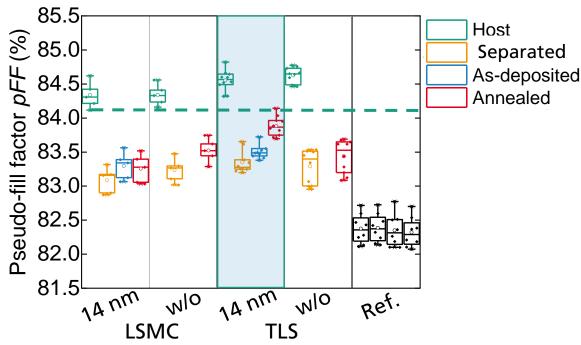




## Suns V<sub>OC</sub> Measurements – Annealing<sup>[1]</sup>

- Host cells measured and pFF values considered
- Similar drops in pFF for TLS and LSMC processes
- Minor increase due to deposition
- Combination of deposition and annealing of TLS-separated cells:
  - $\triangle pFF = +0.6\%_{abs}$
  - 50%<sub>rel</sub> regain (from separated state)

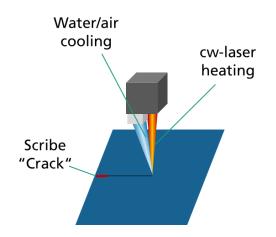


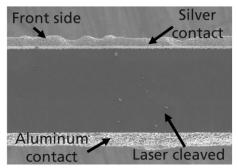


## **Summary**

## Thermal Laser Separation and Passivated Edge Technology

- Photoluminescence imaging used for TLS cleave process optimization
- Losses in open-circuit voltage  $V_{\rm OC}$  and pseudo-fill factor *pFF* mainly attributed to creation of new edges
- Advantage of TLS in comparison to laser scribing and mechanical cleaving (LSMC)
- Post-metallization edge passivation "Passivated Edge Technology" (PET)
- Combination of TLS and PET:
  - Increase in pFF by +0.6%<sub>abs</sub>
     (50%<sub>rel</sub> regain from separated state)
  - Low damage separation required for an effective edge passivation







## **Acknowledgments**

#### Thanks to...

- Fraunhofer ISE colleagues
- The German Federal Ministry for Economic Affairs and Energy for funding "PV-BAT400" (contract no. 0324145)

Puzant Baliozian | Production Technology: Structuring & Metallization

Fraunhofer-Institut für Solare Energiesysteme ISE

www.ise.fraunhofer.de

puzant.baliozian@ise.fraunhofer.de

